



Click [here](#) for the 3D model.

General Information

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| Series | SMD Comm COG HV Flex |
| Style | SMD Chip |
| Description | SMD, MLCC, FT-CAP, Ultra-Stable |
| Features | FT-CAP, Ultra-Stable |
| RoHS | No |
| Prop 65 | WARNING: Cancer and reproductive harm - https://www.p65warnings.ca.gov/ |
| Termination | Flexible Termination With Lead (SnPb) |
| Marking | No |
| Typical Component Weight | 190 mg |
| Shelf Life | 78 Weeks |
| MSL | 1 |

Dimensions

| | |
|----------------------|-----------------|
| L | 5.9mm +/-0.75mm |
| W | 5mm +/-0.4mm |
| T | 1.6mm +/-0.20mm |
| S | 3.5mm MIN |
| B | 0.7mm +/-0.35mm |
| Case Code (EIA / mm) | 2220 / 5651 |

Packaging Specifications

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|--------------------|--------------------------|
| Packaging | T&R, 180mm, Plastic Tape |
| Packaging Quantity | 1000 |

Specifications

| | |
|--|---------------------------|
| Capacitance | 220 pF |
| Measurement Condition | 1 MHz 1.0Vrms |
| Tolerance | 5% |
| Voltage DC | 3000 VDC |
| Dielectric Withstanding Voltage | 3,600 VDC |
| Temperature Range | -55/+125°C |
| Temp. Coefficient | COG |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1MegaHz 1.0Vrms |
| Dissipation Factor | 0.1% 1 MHz 1.0Vrms |
| Aging Rate | 0% Loss/Decade Hour |
| Insulation Resistance | 100 GOhms |

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